

Product Change Notification

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Printed form FC32S00970 / Rev L

Product Change Notification Number: GC170751

Date: February 16th, 2017

Title: PC8640 migration to lead-free bumps

Product Identification: all PC(X)8640__GH__ references ,

PC8640DFGH1000HE	PC8640DVGH1067KE	PC8640MGH1250HEZB6
PC8640DFGH1000HEM3	PC8640DVGH1067NE	PC8640VGH1250HC
PC8640DFGH1067NC	PC8640DVGH1250HE	PC8640VGH1250HE
PC8640DFGH1067NE	PC8640FGH1067NE	PCX8640FGH1067NCG
PC8640DFGH1067NE	PC8640FGH1067NEG5	
PC8640DMGH1250HE	PC8640MGH1250HE	

Reason for Change:

Other

Design

Manufacturing Location

Processing

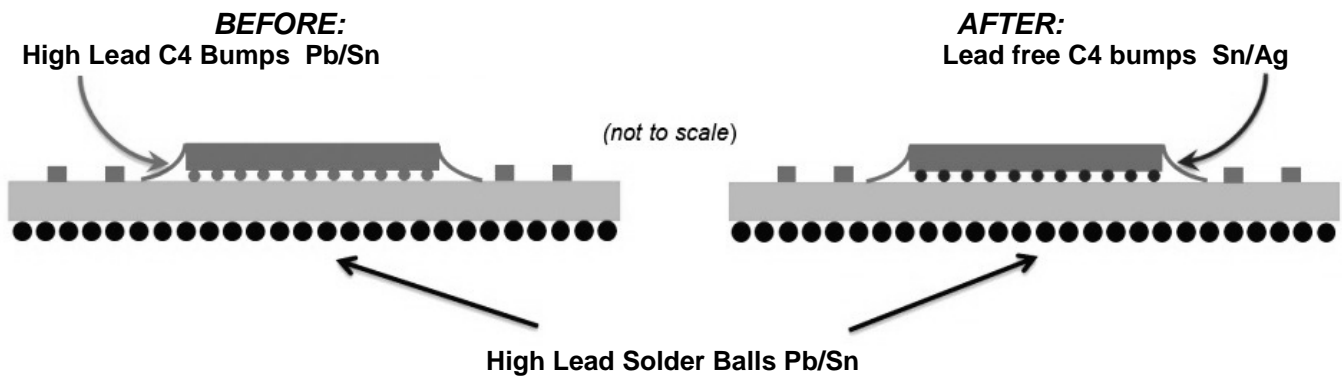
Quality/Reliability

Logistics

Material

Change Description:

NXP has announced (*) the replacement of the leaded C4 bumps by Lead free C4 bumps on the 8640 product family. Only bumps (die-to-package) change, solder balls (package-to-board) remain unchanged.



(*) Reference NXP Quality - 201701040DN - Discontinuation Notification February 03rd 2017.

Identification Method to Distinguish Change:

The product change will be identified by a specific package code to distinguish the die bump metallurgy options. "GH" string will be replaced by "JH". For example PC8640DFGH1067NE becomes PC8640DFJH1067NE.

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Qualification Data for the JH package option:

available will be available not applicable
January 2018

“JH” unqualified samples: available will be available not applicable
PCX8640__JH__ Target June 2017

“JH” qualified samples: available will be available not applicable
PC8640__JH__ Target December 2017

Quantifiable Impact on Quality & Reliability:

This change does not affect the fit, form, functions of the part and the electrical characteristics remain unchanged. The C4 bumps composition is the only material affected by this change. The composition of all other materials used in this product remains unchanged. The die revision remains unchanged. No impact on reliability is expected.

Implementation Date**:

Last orders to e2v for the GH package must be placed until May 17th 2017 to comply with NXP deadline. e2v shipments shall be no later than November 17th 2017.

Lead-time shall be confirmed at order entry. Please note that due to the LBO nature of such order, any lead-time will be definitively committed upon confirmation by NXP of its materials shipment dates to e2v

***The Estimated Implementation Date is the forecasted date that a customer may expect to receive changed product. This is determined by the estimated date of inventory depletion on the PCN issue date. This may be affected by fluctuations in supply and demand. Consequently, although customers should be prepared to receive changed product on this date, e2v semiconductors will continue to ship pre-changed product until a time in which inventory has been depleted. This may result in pre-changed product being shipped to customers after this forecasted date.*

e2v semiconductors contact:

	Quality	Marketing
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Would you need further information, please contact also your local e2v sales representative for your product availability requirements

APPROVAL by TRB

e2v semiconductors will deem this change accepted unless specific conditions of acceptance are provided in writing within 30 days from the date of this notice. All correspondence must be sent to the contact e-mail addresses indicated above.

e2v semiconductors assumes no responsibility for any errors that may appear in this document.

The supply of products will be subject to e2v general terms and conditions of sale or any specific contractual terms agreed between the parties.

The collect of contact and email addresses is key for e2v. e2v must keep informed its customers from its production evolution from introduction to change (PCN) up to phasing out (Discontinuation Notice and EoL). Do not hesitate to provide to us any central or desk email address you feel important to secure the wide diffusion of such information.

For a list of available PCN and EOL announcements, please consult our web site :

<http://www.e2v.com/products/semiconductors/obsolescence-planning-slim/>